

Title (en)
ARRANGEMENT OF AN ELECTRICAL COMPONENT AND A FILM COMPOSITE LAMINATED ON THE COMPONENT AND METHOD FOR PRODUCTION OF THE ARRANGEMENT

Title (de)
ANORDNUNG EINES ELEKTRISCHEN BAUELEMENTS UND EINES AUF DEM BAUELEMENT AUFLAMINIERTEN FOLIENVERBUNDS UND VERFAHREN ZUR HERSTELLUNG DER ANORDNUNG

Title (fr)
ENSEMBLE CONSTITUE D'UN COMPOSANT ELECTRIQUE ET D'UN COMPOSITE A BASE DE FILMS CONTRECOLLE SUR CE COMPOSANT ET PROCEDE DE PRODUCTION DE CET ENSEMBLE

Publication
EP 1908106 A1 20080409 (DE)

Application
EP 06764127 A 20060710

Priority
• EP 2006064061 W 20060710
• DE 102005034873 A 20050726

Abstract (en)
[origin: WO2007012558A1] The invention relates to an arrangement of at least one electrical component and at least one film composite laminated on a component surface, comprising at least one electrically-insulating plastic insulation film. The arrangement is characterised in that the film composite comprises at least one electrically-conducting plastic conducting film with at least one electrically conducting conductor. The invention further relates to a method for production of the arrangement. The plastic conducting film has a high-ohmic resistance. The above is of application in planar large-surface electrical contacting technology for the production of modules with power semiconductors. In this technology plastic films are laminated on the components. An electrical contacting of the components is achieved by means of the plastic films. According to the invention, a low lateral electrical conductivity is achieved, such that an electrical charging of the plastic films required for the contacting technology is prevented on operation of the component or the module.

IPC 8 full level
H01L 23/538 (2006.01); **H01L 21/60** (2006.01); **H01L 23/60** (2006.01); **H01L 23/62** (2006.01)

CPC (source: EP US)
H01L 23/3735 (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H01L 23/62** (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 2224/2402** (2013.01 - EP US); **H01L 2224/24051** (2013.01 - EP US); **H01L 2224/24226** (2013.01 - EP US); **H01L 2224/82039** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01038** (2013.01 - EP US); **H01L 2924/01056** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/1301** (2013.01 - EP US); **H01L 2924/1305** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US); **H01L 2924/15787** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H01L 2924/3011** (2013.01 - EP US); **Y10T 156/10** (2015.01 - EP US)

Citation (search report)
See references of WO 2007012558A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2007012558 A1 20070201; DE 102005034873 A1 20070208; DE 102005034873 B4 20130307; EP 1908106 A1 20080409; US 2010044889 A1 20100225; US 7932585 B2 20110426

DOCDB simple family (application)
EP 2006064061 W 20060710; DE 102005034873 A 20050726; EP 06764127 A 20060710; US 98952806 A 20060710